Product Change Notification

108652 - 02

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**108652 - 02**
Change Title:	**D945GCLF, PCN 108652-02, Product Design, PCB with component and BIOS changes, Reason for Revision: MCH Heatsink change is being included as originally planned**
Date of Publication:	**September 10, 2008**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Sep 11, 2008

Description of Change to the Customer:

Reason for Revision: MCH Heatsink change is being included as originally planned

The heat sink for the MCH at HS1UB will be replaced with a new lower profile version.

Update BIOS to LF94510J.86A.0103
To access release notes or a copy of the BIOS for evaluation please go to http://developer.intel.com/products/motherboard/D945GCLF/tools.htm

A clock generator (by IDT) will be included as an alternate vendor at location U1CK.

The PCB will be changed to enhance manufacturability and with this change the following component changes will be made:
A 1.0 uF capacitor will be added at location C48PR.
A 0.10 uF capacitor will be added at location C93LH.
The capacitors at locations C70LB and C30UB will be changed from 1.0 uF to .01 uF.
The 22.0 uF capacitor at locations C5LN is being moved to C6LN.
The 22.0 uF capacitor at location C110LH is being replaced with 33.0 uF.
The resistors at location 334BU, R125LH and R51LB are being moved to location R34BU, R215LH and R52LB.
The resistors at locations C120LH, R119LH, and R118LH have been removed.
A 4.7 k ohm resistor is being added to location R120LH.
A 560 ohm resistor is being added to location R136LH.
A 1.2 k ohm resister is being added at location R216LH.
A 0.0 ohm resistor is being added at location R20BU.

The polyswitch at location R123BU is be moved to RT6BU.

The transistor at location Q14LH has been removed and transistors will be added at locations Q12LH and Q16LH.

Customer Impact of Change and Recommended Action:

These changes have been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. It is recommended that customers evaluate this new BIOS to ensure a smooth transition.

Intel is not recommending additional qualification of these changes on platforms received from Intel. This change is not expected to cause a change to the Microsoft* Windows* operating system's software driver stack. No expected OS image change.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BLKD945GCLF	896267	E27042-306	E27042-400
BOXD945GCLF	896268	E27042-306	E27042-400
LAD945GCLF	896269	E27044-308	E27044-400
LAD945GCLFS2	899630	E46423-306	E46423-400

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
August 20, 2008	00	Originally Published PCN
August 27, 2008	01	Heatsink changes are being postponed.
September 10, 2008	02	MCH Heatsink change is being included as originally planned